

ELECTRONIC PACKAGE, HEATER BLOCK AND METHOD

ABSTRACT OF THE DISCLOSURE

An electronic package and method furnish shorter wire bonds for smaller chips by increasing the length of the leads and decreasing the size of the paddle. A portion of each lead is reduced in thickness such that polymeric material exposes only a portion of the lead, e.g., that portion that meets industry standards. The portion having a reduced thickness extends further from the thicker portion toward the die paddle than in conventional packages. Since the wire bonds are shorter, the electronic package exhibits less inductance and, hence, increased performance. A heater block used to fabricate the electronic package having raised heating sections for the thinner leads is also included.